

REMARKS

Reconsideration of the above-referenced application in view of the following remarks is respectfully requested.

Claims 1-11 were pending in this application. Non-elected Claims 6-11 are hereby cancelled without prejudice. New Claims 12-16 have been added.

Claim 1 stands rejected under 35 U.S.C. 102(b) as being anticipated by Chapman, et al. (U.S. Patent No. 6,059,172). Claim 1 includes the step of substantially aligning each of said conductive bump contact areas with at least one conductive bump, wherein the step of substantially aligning said conductive bump contact areas with at least one of said conductive bumps comprises the step of vibrating at least a portion of said substrate .

Chapman does not teach or suggest such a step. The Examiner refers to Chapman's Figure 5, but that figure does not teach or suggest vibrating at least a portion of a substrate. Therefore, Applicant respectfully submits that Claim 1 is patentable over Chapman.

Claims 2, 3, 4, and 5 stand rejected under 35 U.S.C. 103(a) as being unpatentable over Chapman in view of Kuroda, et al. (U.S. Patent No. 5,205,032). Claim 2 includes the feature where, in the method of Claim 1, the step of vibrating comprises ultrasonically vibrating at least a portion of a substrate. As argued above, Chapman does not teach or suggest a step of vibrating at least a portion of a substrate. The Examiner cites Kuroda for its teaching of ultrasonic vibration. However, Kuroda's teaching does not cure the deficiency of Chapman with regard to Claim 1. Claim 2 depends from Claim 1 and is therefore patentable over the cited combination of references for at least the reasons presented above. Claims 4 and 5 also depend from Claim 1 and are therefore patentable over the cited combination at least by virtue of their dependence from a patentable base claim.

Claim 3 includes the feature where, in the method of Claim 2, the ultrasonic vibrating step comprises vibrating a first end, a second end, and a third end of a film strip on which at least one of the substrates is disposed. Neither Chapman nor Kuroda teach or suggest such a step. Moreover, the combination of those references is deficient in teach or suggesting the claimed step. Therefore, Applicant submits that Claim 3 is patentable over Chapman in view of Kuroda.

New Claim 12 includes the steps of Claim 1, with the additional step of "reflowing said conductor bumps disposed on said conductive bump contact areas." Support for this step may be found on page 7 of the specification in lines 27-30. New Claims 13-16 depend from Claim 12 and are therefore patentable over the cited references at least by virtue of their dependence upon a patentable base claim.

Applicant respectfully requests reconsideration and withdrawal of the rejections and allowance of Claims 1-5 and 12-16. If the Examiner has any questions or other correspondence regarding this application, Applicant requests that the Examiner contact Applicant's attorney at the below listed telephone number and address.

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Respectfully submitted,



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